

Amendments to the Claims:

Applicant proposes to amend claims 3, 7, 12, 15, 16, 18, 20, and 21. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

Claims 1-2 (Canceled)

3. (Currently amended) A transfer molding apparatus comprising:
first and second members configured to be assembled with one another;
at least one encapsulant restraining cavity formed in at least one of saidthe first and second
members, saidthe at least one cavity extending longitudinally in a non-horizontal
orientation;
at least one gate at a lower portion of saidthe at least one cavity;
at least one vent at an upper portion of saidthe at least one cavity; and
wherein saidthe at least one cavity includes at least one surface with recesses formed therein,
each of saidthe recesses having an imperforate boundary wall that is sized and configured
to ~~at least partially~~ substantially conformally receive a portion of one of a plurality of
conductive structures protruding from a substrate positionable in saidthe at least one
cavity.

Claims 4-6 (Canceled)

7. (Currently amended) A transfer molding apparatus comprising:
first and second members to be assembled with one another;

at least one encapsulant restraining cavity formed in at least one of saidthe first and second members, saidthe at least one cavity extending longitudinally in a substantially vertical orientation;

at least one gate at a lower portion of saidthe at least one cavity;

at least one vent at an upper portion of saidthe at least one cavity; and

wherein saidthe at least one cavity includes at least one surface with recesses formed therein, each of saidthe recesses defined by an imperforate boundary wall that is sized and configured to substantially conformally receive a portion of one of a plurality of conductive structures protruding from a substrate positionable in saidthe at least one cavity.

Claims 8-11 (Canceled)

12. (Currently amended) A transfer molding apparatus for molding a substrate in a substantially vertical orientation, the apparatus comprising:

a first member and a second member configured to be assembled with one another, each of saidthe first member and saidthe second member having an inside surface and an outside surface;

multiple encapsulant restraining cavities each formed in saidthe inside surface of at least one of saidthe first member and saidthe second member, each of saidthe multiple cavities sized and configured for the substrate to be disposed therein, saidthe multiple cavities extending longitudinally in a non-horizontal orientation;

at least one gate formed in any one of saidthe first member and saidthe second member extending from a lower portion of each of saidthe multiple cavities; at least one vent formed in any one of saidthe first member and saidthe second member extending from an upper portion of each of saidthe multiple cavities; and

wherein at least one of saidthe multiple cavities includes recesses formed in saidthe inside surface on saidthe at least one of saidthe first member and saidthe second member, each of saidthe recesses defined by an imperforate boundary wall that is sized and configured

to substantially conformally ~~at least partially~~ receive a portion of one of a plurality of conductive structures protruding from the substrate positionable in ~~said~~the at least one of ~~said~~the multiple cavities.

Claims 13-14 (Cancelled)

15. (Currently amended) The transfer molding apparatus of claim 12, wherein ~~said~~the multiple cavities are configured and longitudinally oriented to provide a substantially vertical flow for encapsulation of the substrate positionable in ~~said~~the multiple cavities.

16. (Currently amended) The apparatus according to claim 3, wherein ~~said~~the at least one cavity comprises a substantially vertically oriented cavity.

Claim 17 (Cancelled)

18. (Currently amended) The apparatus according to claim 7, wherein ~~said~~the at least one cavity is configured to provide a substantially vertical flow for encapsulation of a substrate positionable in ~~said~~the at least one cavity.

Claim 19 (Cancelled)

20. (Currently amended) The transfer molding apparatus of claim 12, wherein each of ~~said~~the multiple cavities comprises a substantially vertically oriented cavity.

21. (Currently amended) The transfer molding apparatus of claim 12, wherein each of ~~said~~the multiple cavities includes a longitudinal length substantially oriented along a substantially vertical orientation.

22. (Previously presented) The transfer molding apparatus of claim 3, wherein the plurality of conductive structures comprise pillars or columns.

23. (Previously presented) The transfer molding apparatus of claim 7, wherein the plurality of conductive structures comprise pillars or columns.

24. (Previously presented) The transfer molding apparatus of claim 12, wherein the plurality of conductive structures comprise pillars or columns.

Claims 25-27 (Cancelled)